

# **Enhancement Mode N-Channel Power MOSFET**

PDFN5X6/NMOS/40V/ $\pm$ 20V/1.5V/210A/1.6m $\Omega$ 

Rev0.1





# 40V, 1.6mΩ, 210A, N-Channel Enhancement MOSFET

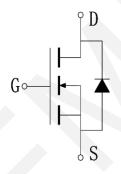
#### 1.Features

- ◆ 40V MOSFET technology
- ◆ Low on-state resistance
- Fast switching
- ♦ Vgs±20V

- ◆ Power Switching Application
- Load Switching



V <sub>DS</sub>	R <sub>DS(on)</sub> Typ.	I <sub>D</sub> Max.
40V	1.6mΩ @ 10V	0404
	2.1mΩ @ 4.5V	210A



Schematic Diagram

## 3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP40210KPA	WP40210KPA	PDFN5X6	5,000	50,000

#### 4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	$V_{ extsf{DSS}}$	40	V
Gate to Source Voltage	V <sub>GSS</sub>	±20	V
Drain Current (DC)	ID	210	А
Drain Current (Pulse), PW≤300μs	<b>I</b> DP	840	Α
Total Dissipation	P <sub>D</sub>	120	W
Avalanche Energy, Single Pulsed	Eas	420	mJ
Junction Temperature	Tj	150	°C
Storage Temperature	$T_{stg}$	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



## **5.Thermal Resistance Ratings**

Parameter	Symbol	Value	Unit
Junction to Case	Rejc	1.0	°C/W

Note 2: When mounted on 1 inch square copper board  $t \le 10$ sec The value in any given application depends on the user's specific board design.

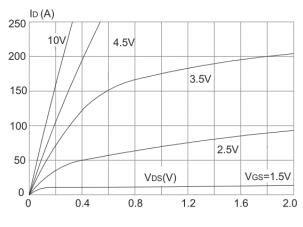
## 6.Electrical Characteristics at Ta=25°C (Note 3)

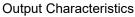
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$I_D = 250 \mu A$ , $V_{GS} = 0 V$	40	-	-	V
Zero-Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> = 0V	-	-	1	μΑ
Gate to Source Leakage Current	Igss	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250µA	1.0	1.5	2.5	V
Static Drain to Source On-State	Б	I <sub>D</sub> =30A, V <sub>GS</sub> = 10V	-	1.6	2.0	mΩ
Resistance	R <sub>DS(on)</sub>	I <sub>D</sub> = 20A, V <sub>GS</sub> = 4.5V	-	2.1	3.0	mΩ
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V,	-	14.7	-	nF
Output Capacitance	Coss	V <sub>DS</sub> =20V,	-	843	-	pF
Reverse Transfer Capacitance	Crss	Frequency=1.0MHz	-	830	-	pF
Turn-ON Delay Time	t <sub>d(on)</sub>	$V_{DD} = 20V, R_L = 1\Omega,$ $V_{GS} = 10V, I_D = 30A,$ $R_{GEN} = 3\Omega$	-	13	-	ns
Rise Time	tr		-	9	-	ns
Turn-OFF Delay Time	t <sub>d(off)</sub>		-	101	-	ns
Fall Time	tf		-	15	-	ns
	Qg	V <sub>DS</sub> =20V, V <sub>GS</sub> = 10V, I <sub>D</sub> =30A	-	95	-	nC
Total Gate Charge	Qgs		-	15	-	nC
	Q <sub>gd</sub>		-	19	-	nC
Diode Forward Voltage	$V_{FSD}$	I <sub>S</sub> =30A, V <sub>GS</sub> = 0	-	-	1.2	V

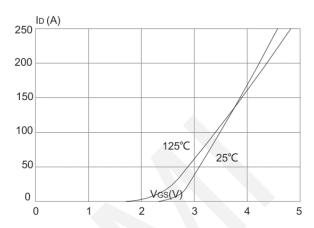
Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



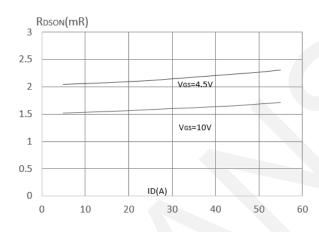
## 7. Typical electrical and thermal characteristics



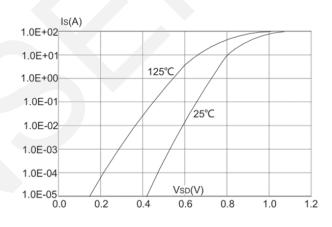




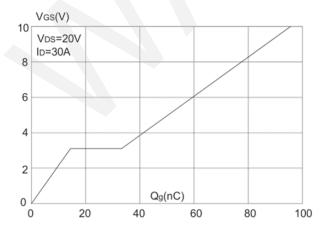
Typical Transfer Characteristics



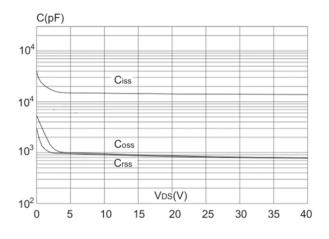
On-resistance vs. Drain Current



**Body Diode Characteristics** 

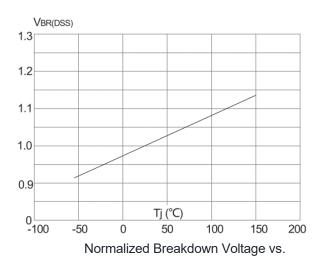


Gate Charge Characteristics

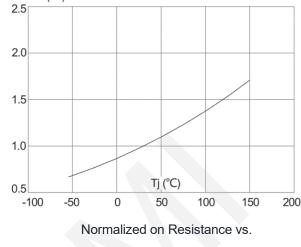


Capacitance Characteristics



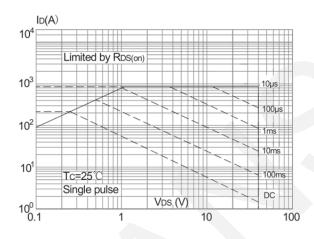


Junction Temperature

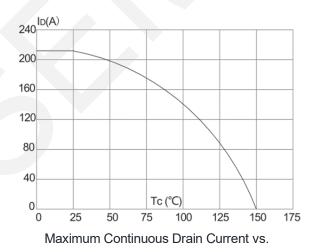


Ros(on)

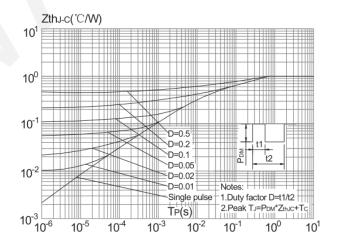
Junction Temperature



Maximum Safe Operating Area



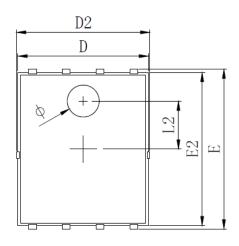
Case Temperature

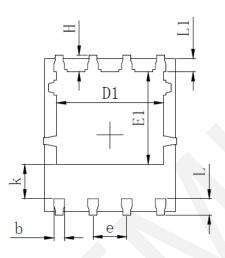


Maximum Effective Transient Thermal Impedance, Junction-to-Case



# 8.Package Dimensions





SYMBOL		MILLIMETER		
SIMDOL	MIN	Тур.	MAX	
A	0. 900	1. 000	1. 100	
A1	0. 254 REF.			
A2		0~0.05		
D	4. 824	4. 900	4. 976	
D1	3. 910	4. 010	4. 110	
D2	4. 924	5. 000	5. 076	
Е	5. 924	6. 000	6. 076	
E1	3. 375	3. 475	3. 575	
E2	5. 674	5. 750	5. 826	
b	0. 350	0. 400	0. 450	
e	1.270 TYP.			
L	0. 534	0. 610	0. 686	
L1	0. 424	0. 500	0. 576	
L2	1.800 REF.			
k	1. 190	1. 290	1. 390	
Н	0. 549	0. 625	0. 701	
θ	8°	10°	12°	
ф	1. 100	1. 200	1.300	
d			0. 100	



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